



Clock Generator for Power PC Designs with SDRAM and USB Support

Preliminary Product Information

PIN DESCRIPTION

Xin, Xout - These pins form an on-chip reference oscillator when connected to terminals of an external parallel resonant crystal (nominally 14.318 MHz). Xin may also serve as input for an externally generated reference signal.

Sel0, Sel1, and Sel2 - Standard frequency select inputs. These inputs have internal pull-ups.

CPU(1:4) - Low skew (<250 pS) clock outputs for host frequencies such as CPU, Chipset, Cache, etc... CPU1-CPU4 voltage level is controlled by VDDCPU. CPU buffers have 60 mA switching current at 3.3V.

SDRM(1:12) - Low skew (<250 pS) clock outputs for SDRAM. Voltage level is controlled by VDDRM. SDRAM buffers have 60 mA switching current at 3.3V.

IOAPIC - Buffered output clock of the crystal. This buffer has 60 mA switching current at 3.3V. Voltage level is controlled by VDDIO.

PCI(1:8) - Low skew (<250pS) clock outputs for PCI frequencies. This buffer voltage level is controlled by VDD. All these outputs have 60 mA switching current at 3.3V.

REF(1:2) - Buffered output of on-chip reference. Outputs have 60mA switching current at 3.3V.

48MHz - Frequency output for USB.

VSS - Circuit ground.

VDD - Positive power supply.

VDDCPU - 3.3V/2.5V logic level control for CPU(1:4) outputs. Voltage cannot be greater than VDD.

VDDRM - 3.3V/2.5V logic level control for SDRAM(1:12) outputs. Voltage cannot be greater than VDD.

VDDIO - 3.3V/2.5V logic level control for IOAPIC output. Voltage cannot be greater than VDD.

MAXIMUM RATINGS

Voltage Relative to VSS:	-0.3V
Voltage Relative to VDD:	0.3V
Storage Temperature:	-65°C to + 150°C
Ambient Temperature:	-55°C to +125°C
Maximum Power Supply:	7V

This device contains circuitry to protect the inputs against damage due to high static voltages or electric field; however, precautions should be taken to avoid application of any voltage higher than the maximum rated voltages to this circuit. For proper operation, Vin and Vout should be constrained to the range:

$$VSS < (V_{in} \text{ or } V_{out}) < VDD$$

Unused inputs must always be tied to an appropriate logic voltage level (either VSS or VDD).



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ELECTRICAL CHARACTERISTICS

Characteristic	Symbol	Min	Typ	Max	Units	Conditions
Input Low Voltage	VIL	-	-	0.8	Vdc	-
Input High Voltage	VIH	2.0	-	-	Vdc	-
Input Low, or High Current with Pull- up or Pull-down	IIL, IIH	-	-	5 \pm 50	μ A	S0-S2 Inputs
Output Low Voltage IOL = 12mA	VOL	-	-	0.4	Vdc	All Outputs
Output High Voltage IOH = 12mA	VOH	2.4	-	-	Vdc	All Outputs
Tri-State leakage Current	Ioz	-	-	10	μ A	All Outputs
Dynamic Supply Current	Icc	-	67	-	mA	CPU = 66.6 MHz, PCI = 33.3 Mhz No Load
Short Circuit Current	ISC	25	-	-	mA	1 output at a time - 30 seconds
VDD = VDDCPU = VDDRM = 3.3V\pm5%, TA = 0°C to +70°C						

SWITCHING CHARACTERISTICS

Characteristic	Symbol	Min	Typ	Max	Units	Conditions
Output Rise (0.4V - 2.0V) and Fall (2.0V-0.4V) time	tTLH, tTHL	-	-	1.2	ns	15 pf Load CPU and PCI outputs
Output Duty Cycle	-	45	50	55	%	Measured at 1.5V
CPU to PCI Offset	tOFF	0	-	2	ns	15 pf Load Measured at 1.5V
Skew All CPU Output	tSKEW	-	-	250	ps	15 pf Load Measured at 1.5V
Skew All PCI Outputs	tSKEP	-	-	350	ps	15 pf Load Measured at 1.5V
Δ Period Cycles, CPU	Δ P	-	-	\pm 250	ps	-
Jitter Absolute, CPU	tjab	-	-	500	ps	-
VDD = VDDCPU = VDDRM = 3.3V\pm5%, TA = 0°C to +70°C						



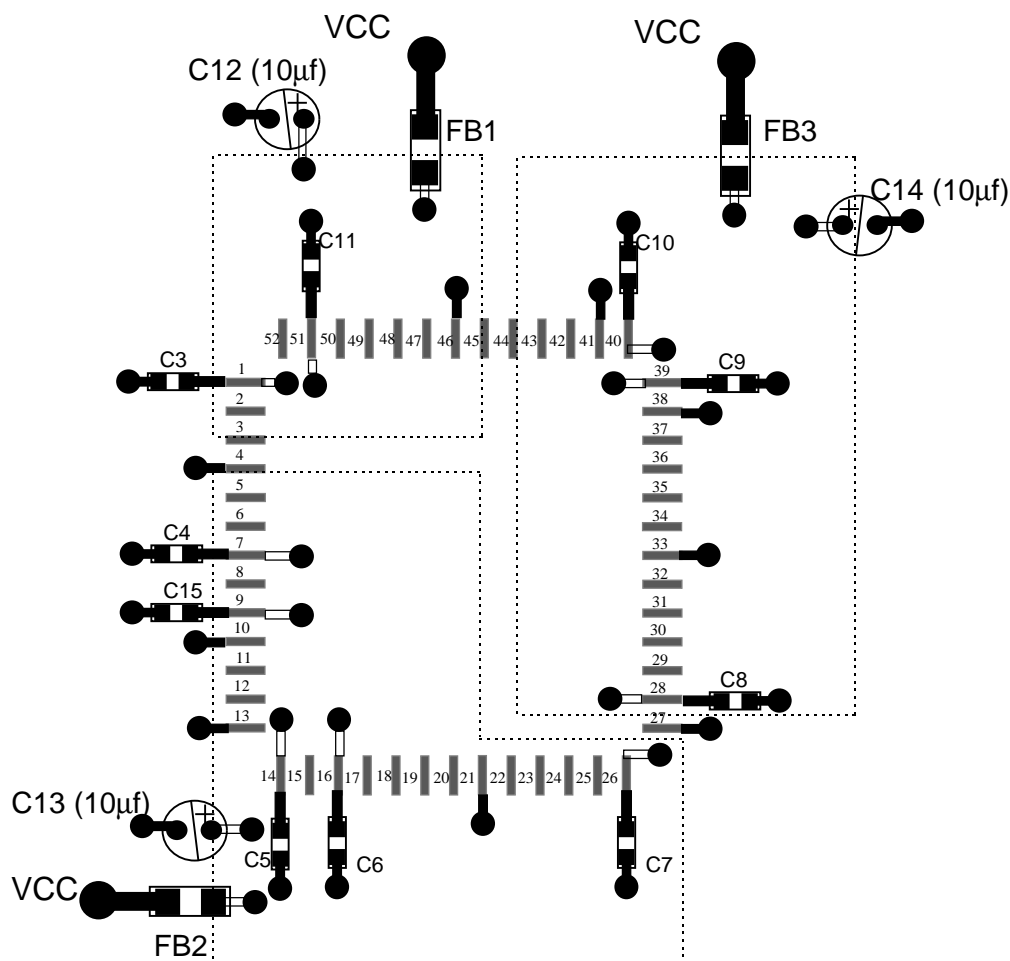
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PCB LAYOUT SUGGESTION

IMISC662

- Via to GND plane
- Via to VDD island
- Via to VCC plane



This is only a layout suggestion for best performance and lower EMI. The designer may choose a different approach such as using VDD traces instead of islands (dashed areas). Also, the designer may choose to use less than three beads. Regardless of which way the layout is implemented, Bypass caps : C3, C4, C5, C6, C7, C8, C9, C10, C11 and C15 (all 0.1 μ F) should always be used and placed as close to their VDD pins as possible.

NOTES

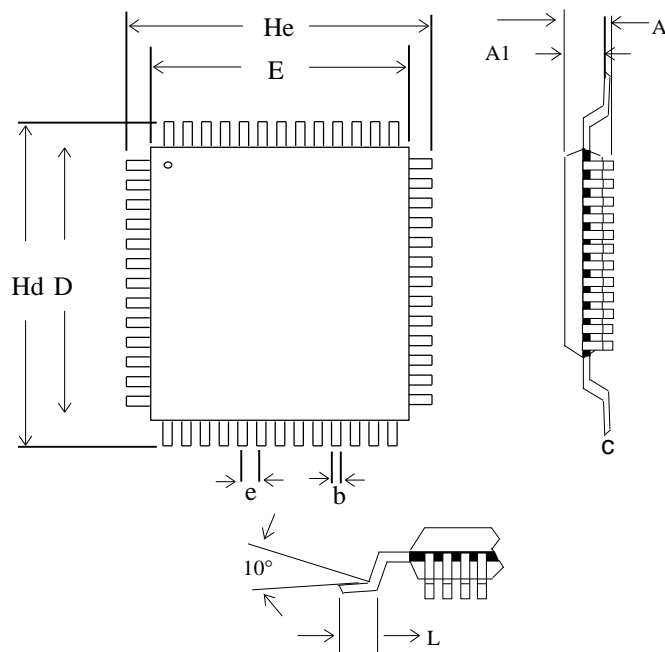
1. POWER SUPPLY BYPASS CAPS (0.1UF) MUST BE POSITIONED AS CLOSE AS POSSIBLE TO VDD PINS TO BE EFFECTIVE.
2. BYPASS CAPS MUST BE LOW LEAKAGE SUCH AS MULTILAYER CERAMIC Z5U OR X7R MATERIAL WHICH ALSO RESULTS IN LOWER IMPEDANCE AT HIGH FREQUENCY.
3. FB: FERRITE BEAD



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PACKAGE DRAWING AND DIMENSIONS



52 PIN QFP OUTLINE DIMENSIONS

SYMBOL	INCHES			MILLIMETERS		
	MIN	NOM	MAX	MIN	NOM	MAX
A	.075	.081	.087	1.90	2.05	2.20
A1	.056	.058	.060	1.43	1.48	1.53
D	.389	.393	.397	9.90	10.00	10.10
E	.389	.393	.397	9.90	10.00	10.10
b	.008	0.012	0.016	0.20	0.30	0.40
Hd	.537	.547	.557	13.65	13.90	14.15
He	.537	.547	.557	13.65	13.90	14.15
e	.025			.65		
L	.025	.031	.037	.65	.80	.95

ORDERING INFORMATION

Part Number	Package Type	Production Flow
IMISC662AAB	52 PIN QFP	Commercial, 0°C to +70°C

Note: The ordering part number is formed by a combination of device number, device revision, package style, and screening as shown below.

Marking: Example: IMI
SC662AAB
Date Code, Lot #

IMISC662AAB

- Flow
B = Commercial, 0°C to + 70°C
- Package
A= QFP
- Revision
- IMI Device Number